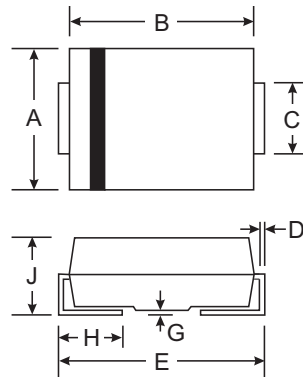


Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed:
250°C/10 seconds at terminals

Mechanical Data

- **Case:** JEDEC DO-214AA molded plastic body
- **Terminals:** leads solderable per MIL-STD-750, Method 2026
- **Polarity:** Color band denotes cathode end
- **Mounting Position:** Any
- **Weight:** 0.005 ounce, 0.138 grams



SMB		
Dim	Min	Max
A	3.30	3.94
B	4.00	4.65
C	1.95	2.21
D	0.15	0.40
E	5.00	6.00
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.
Single phase, halfwave, 60Hz resistive or inductive load.

	SYMBOLS	SS22	SS23	SS24	SS25	SS26	SS28	SS210	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	VOLTS
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	VOLTS
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	VOLTS
Maximum average forward rectified current at T_L (see fig.1)	I_{AV}	2.0							Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50.0							Amps
Maximum instantaneous forward voltage at 2.0A	V_F	0.55		0.70		0.85			Volts
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	0.5							mA
		20		10					
Typical junction capacitance (NOTE 1)	C_J	220		180					pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	75.0							°C/W
Operating junction temperature range	T_J	-65 to +125		-65 to +150					°C
Storage temperature range	T_{STG}	-65 to +150							°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

